



Material Content Data Sheet



Sales Product Name	ESD5V0S5US H6327			Issued		29. August 2013		
MA#	MA000844926							
Package	PG-SOT363-6-4			Weight*		6.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		21	
	noble metal	gold	7440-57-5	0.013	0.21		2123	
	inorganic material	silicon	7440-21-3	0.114	1.81	2.02	18131	20275
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		91	
	non noble metal	titanium	7440-32-6	0.003	0.05		457	
	non noble metal	chromium	7440-47-3	0.009	0.14		1370	
	non noble metal	copper	7440-50-8	2.860	45.47	45.67	454693	456611
wire	non noble metal	copper	7440-50-8	0.013	0.21	0.21	2102	2102
encapsulation	organic material	carbon black	1333-86-4	0.030	0.48		4776	
	plastics	epoxy resin	-	0.646	10.27		102683	
	inorganic material	silicondioxide	60676-86-0	2.328	37.01	47.76	370136	477595
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33901	33901
plating	noble metal	silver	7440-22-4	0.060	0.95	0.95	9516	9516
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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